

14 CONNECTION LEAD

13 PLATING

11 COPPER STRIP

12 PLATING

W<sub>2</sub>  
WIDTH OF COPPER STRIP

t<sub>4</sub> THICKNESS OF PLATING

t<sub>3</sub> THICKNESS OF COPPER STRIP

t<sub>4</sub> THICKNESS OF PLATING

B  
CENTER PORTION

A cross-sectional diagram of a connection lead assembly. A central copper strip (11) is sandwiched between two plating layers (12 and 13). The entire assembly is pressed against a silicon wafer (15) by an applied pressure (P), indicated by a downward arrow. A horizontal force (F), indicated by a double-headed arrow, is applied to the copper strip. The contact area between the copper strip and the silicon wafer is labeled as a silver-plated portion (16). The entire assembly is part of a connection lead (14). A label 17 is partially visible at the bottom left.

**FIG. 2B**

13 PLATING

11 COPPER STRIP

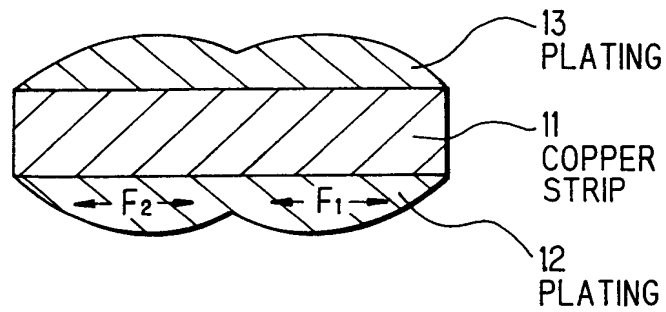
12 PLATING

14 CONNECTION LEAD

15 SILICON WAFER

16 SILVER-PLATED PORTION

**FIG. 3**



**FIG. 4**

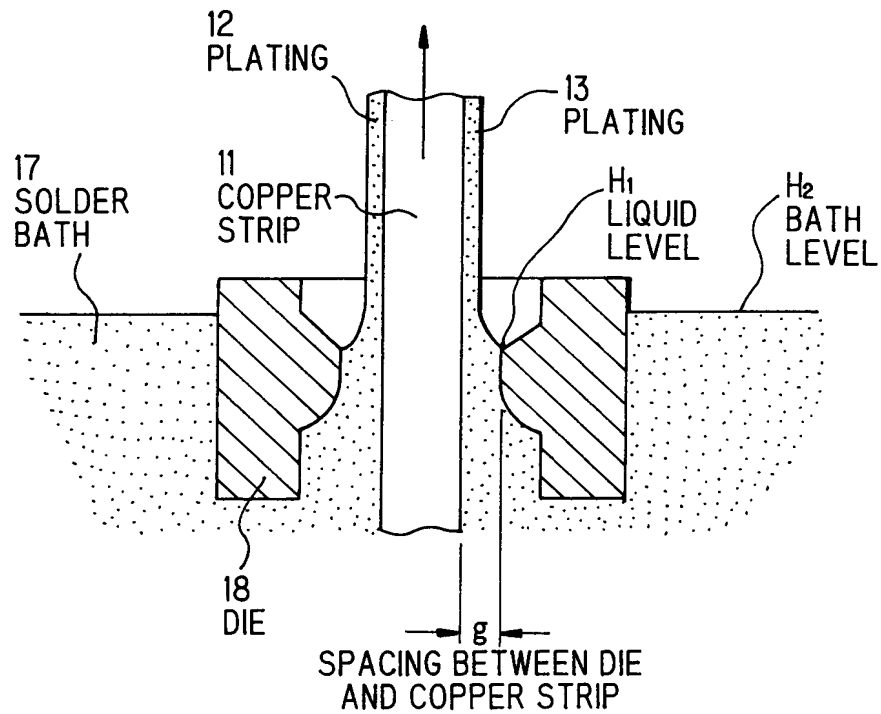
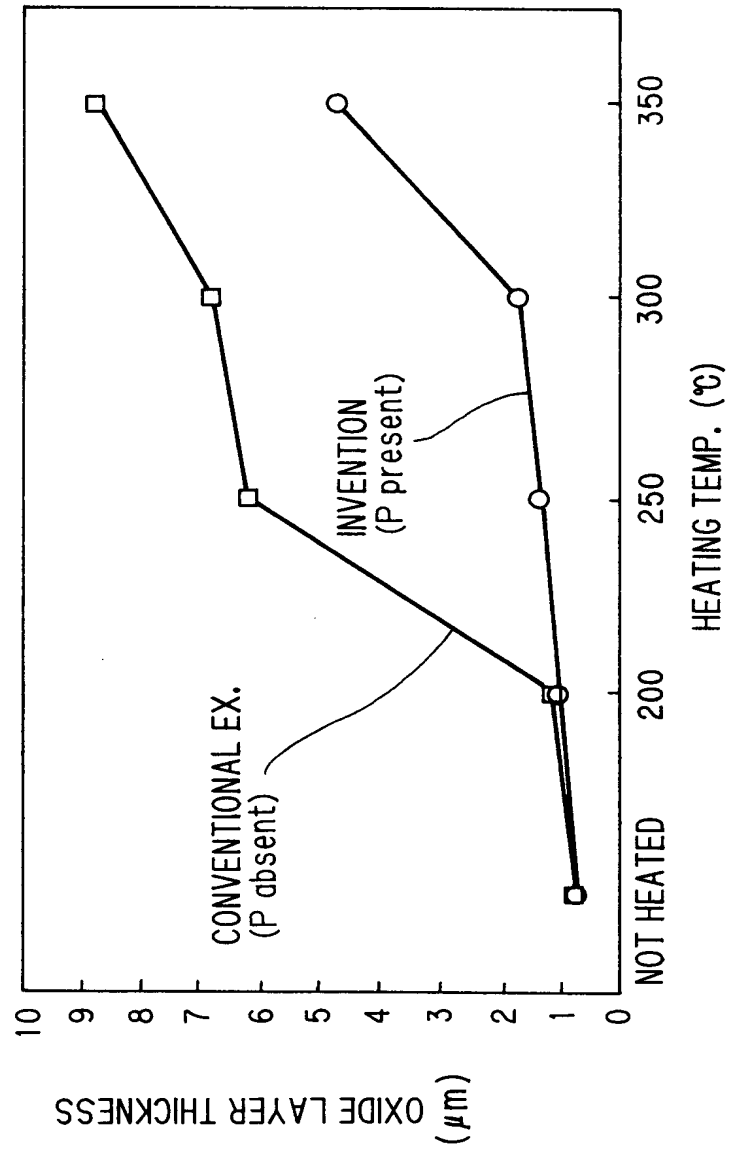
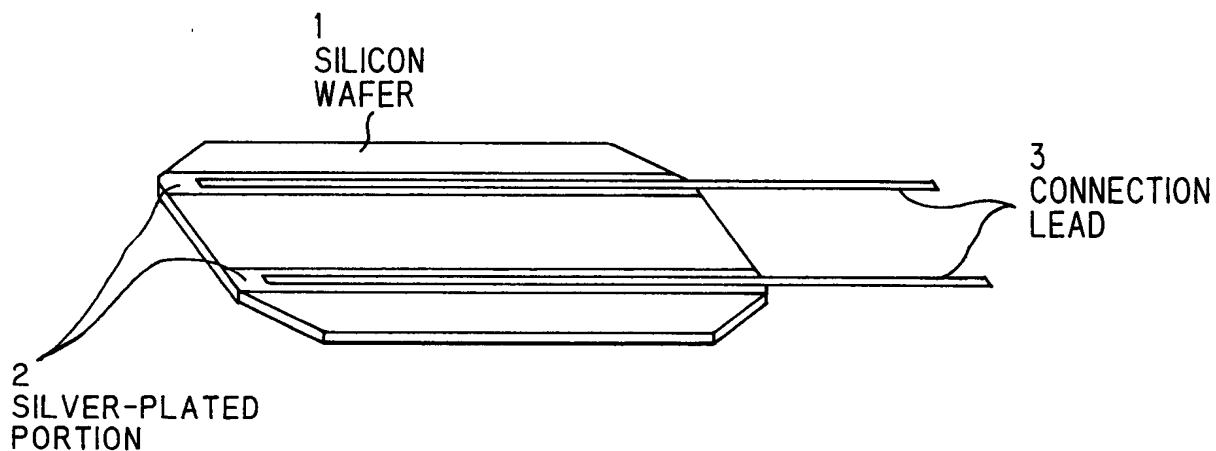


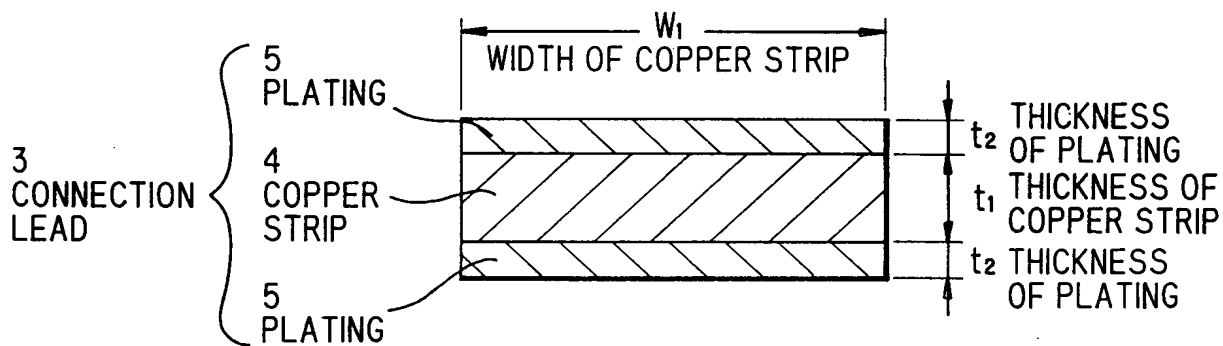
FIG. 5



<sup>4/4</sup>  
**FIG. 6**



**FIG. 7A**



**FIG. 7B**

